BMC Release Notes Form

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Product Name	X13DSF-A
Release Version	01.01.18
Release Date	09/20/2023
Previous Version	01.01.10
Update Category	Enhancement
Dependencies	None
Important Notes	None
Enhancements	N/A
New features	N/A
Fixes	 Fixed taking long time to prepare sensor ready. Improved BMC efficiency, compatibility, and reliability.

Release Notes from Previous Release(s)

01.00.16 (10/28/2022)

Initial release.

01.00.25 (01/04/2023)

- 1. Upgrade X13 crash dump version to 2.0.2
- Support Xilinx U250 GPU, GPU NVIDIA L4 PCIe Card, AOC-S25G6-m2SM, Kioxia_CD6, AOC-SLG4-2H8M2, AOC-S3808L-L8IR, AOC-S3816L-L16IR, Intel PVC GPU, RTX A2000-6G, GPU NVIDIA RTX T1000 4G and GPU NVIDIA RTX T1000 8G.
- 3. Redfish method to set BMC LAN interface.
- 4. Improved BMC efficiency, compatibility and reliability.

01.01.10 (08/09/2023)

- 1. KVM launched and closed MEL should display user ID
- 2. Support Temp sensor reading of RTX 3090 GPU card.
- Retrieve BIOS version from 'OFID'
- 4. Redfish 2020.3 related feature
- BPN-E1S5-126ES2N CPLD firmware updating.
- Support Motherboard CPLD Golden Image Version Display
- 7. Support Motherboard CPLD Golden Image Update

- 8. Task Queue & Task List in storage monitoring
- 9. Auto Daylight Saving Time.
- 10. support HBM sensor reading for NVIDIA GPU H100
- 11. Upgrade the Ethernet Interface version from v1.6.2 to v1.6.3 to align spec.
- 12. Dark Theme update.
- 13. Improved BMC efficiency, compatibility and reliability.

01.01.18 (09/20/2023)

- 1. Fixed taking long time to prepare sensor ready.
- 2. Improved BMC efficiency, compatibility, and reliability.